



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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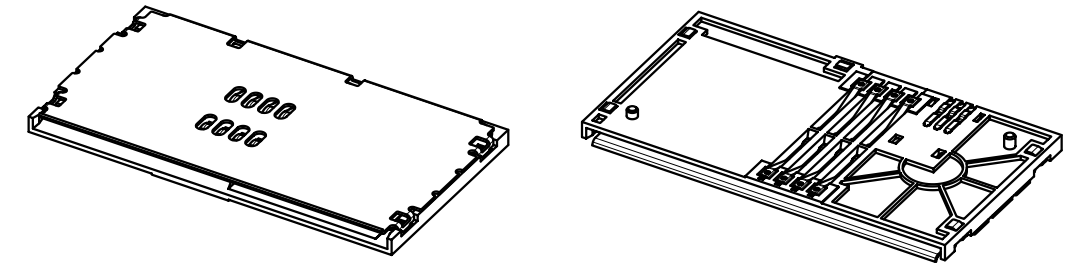
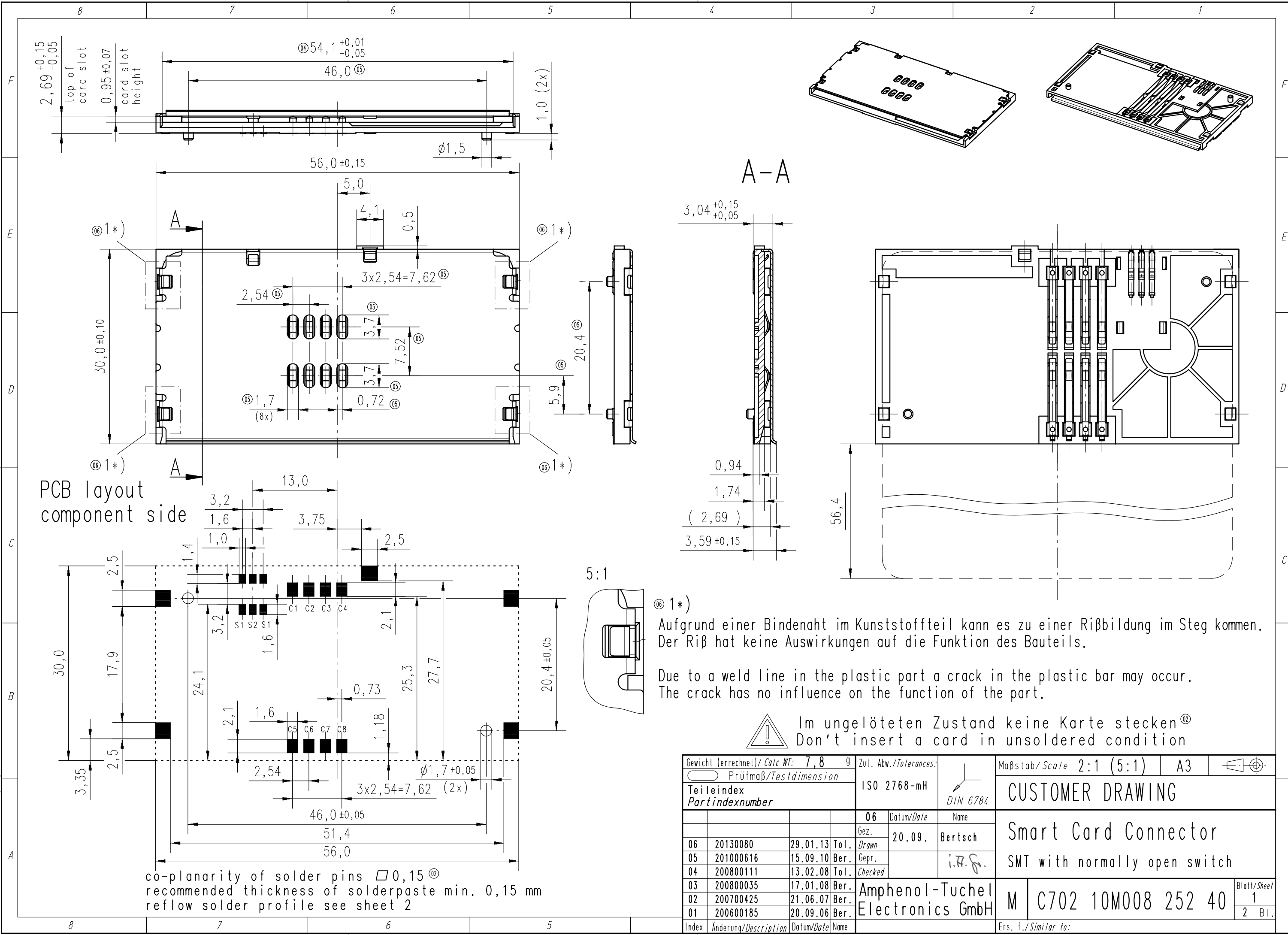
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⑥ 1*) Aufgrund einer Bindenadt im Kunststoffteil kann es zu einer Rißbildung im Steg kommen. Der Riß hat keine Auswirkungen auf die Funktion des Bauteils.
 Due to a weld line in the plastic part a crack in the plastic bar may occur. The crack has no influence on the function of the part.

⚠ Im ungelöteten Zustand keine Karte stecken! Ⓜ
 Don't insert a card in unsoldered condition

co-planarity of solder pins $\square 0,15$ Ⓜ
 recommended thickness of solderpaste min. 0,15 mm
 reflow solder profile see sheet 2

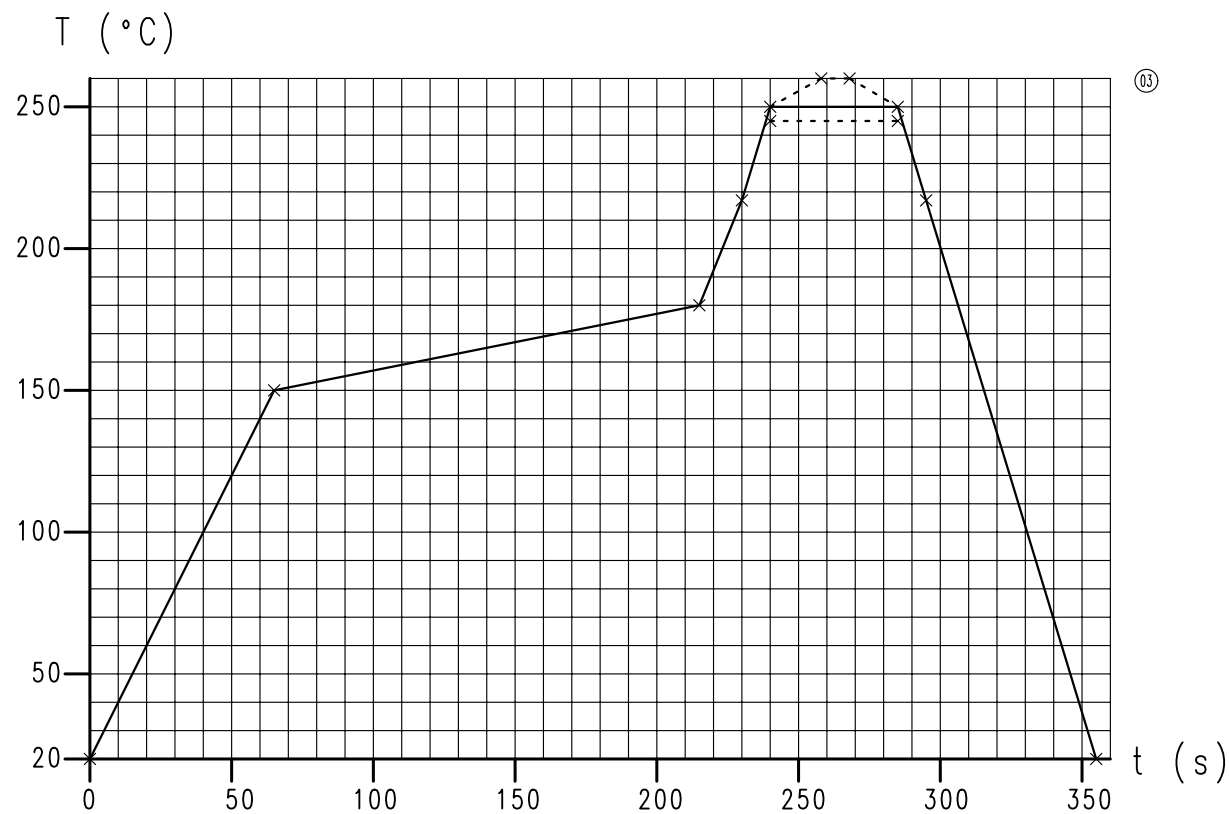
Gewicht (errechnet) / Calc WT: 7,8 9		Zul. Abw. / Tolerances:		Maßstab / Scale 2:1 (5:1)		A3	
Prüfmaß / Testdimension		ISO 2768-mH		DIN 6784		CUSTOMER DRAWING	
Teileindex / Partindexnumber		06		Datum / Date		Name	
06 20130080		29.01.13		20.09.		Bertsch	
05 201000616		15.09.10		Gez.		i.f.g.	
04 200800111		13.02.08		Gepr.		Smart Card Connector	
03 200800035		17.01.08		Checked		SMT with normally open switch	
02 200700425		21.06.07		Ber.		Amphenol-Tuchel Electronics GmbH	
01 200600185		20.09.06		Ber.		M C702 10M008 252 40	
Index		Änderung / Description		Datum / Date		Name	
						Ers. f. / Similar to:	
						Blatt / Sheet 1	
						2 Bl.	

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estimated temperature profile for lead free soldering^{02 03}

Sn (3,0-4,0)Ag (0,5-0,9)Cu solder alloy



Parameter	Specification
Average temperature gradient in preheating	2,5 °C/s
Preheating temperature	150 °C - 200 °C
Soak time	120 s - 180 s
Time above 217 °C	40 s - 120 s
Peak temperature in reflow	245 °C - 260 °C ⁰³
Time at peak temperature	10 s - 50 s
Temperature gradient in cooling	max -5 °C/s

Specification⁰²

DESIGN

type: push-pull, wiping contacts
normally open switch
with positioning studs

GENERAL CHARACTERISTICS

number of contacts: 8 contacts
switch: normally open (no card inserted)
card type: according to ISO 7810 / 7816
card thickness: 0,76 ±0,08 mm
termination: SMT

MATERIALS AND PLATING

insulator: LCP, black
contact plating: Au over Ni

CLIMATIC CHARACTERISTICS

operating temperature: -25 °C to +70 °C
storage temperature: -40 °C to +85 °C
soldering process: reflow soldering

ELECTRICAL CHARACTERISTICS

contact resistance: max. 100 mΩ (data contacts)
max. 1 Ω (switch)
insulation resistance: >10⁹ Ω
high voltage resistance: 500 V AC for 1 minute
rated voltage: <15 V DC
rated current: <1 A

MECHANICAL CHARACTERISTICS

card insertion force: <10 N
card extraction force: >1 N
mechanical lifetime: 100.000 mating cycles
(without corrosion stress)

PACKAGING

packaging: 32 parts per tray
24 trays per carton

Gewicht (errechnet)/ Calc WT: 7,8 g		Zul. Abw./Tolerances:		Maßstab/Scale 2:1 (5:1)		A3			
Prüfmaß/Testdimension		ISO 2768-mH				CUSTOMER DRAWING			
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								Blatt/Sheet 2 Bl.	
								Ers. f./Similar to:	